

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re the Application of:

JOAN K. VRTIS, ET AL.

Application No.:

Filed:

For: **Coated Heat Spreaders**

Art Group: 3729

Examiner: **Tai Van Nguyen**

**INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In accordance with the duty of disclosure, enclosed is a copy of Information Disclosure Statement by Applicant (form PTO/SB/08), which is being submitted concurrently with the Divisional Application. It is respectfully requested that the cited references be considered and that the enclosed copy of PTO/SB/08 be initialed by the Examiner to indicate such consideration and a copy thereof returned to applicant(s). Some or all of the references listed on the enclosed PTO/SB/08 were previously identified in the parent application (Application No. 10/023,073, filed December 20, 2001) and copies of the references were furnished at that time. Accordingly, per 37 CFR §1.98(d)(1) additional copies of those references are not submitted herewith.

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The submission of this Information Disclosure Statement is not to be construed as a representation that a search has been made in the subject application and is not to be construed as an admission that the information cited in this statement is material to patentability.

Please charge any fees due to Deposit Account 02-2666. A duplicate copy of the Fee Transmittal (PTO/SB/17) is enclosed for this purpose.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP



Heather M. Molleur, Reg. No. 50,432

Date:

3/11/04

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Substitute for form 1449A/PTO				Complete if Known	
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b> (use as many sheets as necessary)				Application Number	10/799,204
				Filing Date	03/11/2004
				First Named Inventor	Joan K. Vrtis
				Art Unit	3729
				Examiner Name	Tai Van Nguyen
Sheet	1	of	3	Attorney Docket Number	42P13111D

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. <sup>1</sup>	Document Number Number - Kind Code <sup>2</sup> (if known)	Publication Date Issue Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
TN		US-2002/0009826 A1	01-24-2002	Chien	
		US-2002/0171132 A1	11-21-2002	Buchwalter et al.	
		US-4,858,073	08-15-1989	Gregory	
		US-5,489,805	02-06-1996	Hackitt et al.	
		US-6,008,988	12-28-1999	Palmer	
		US-6,197,859 B1	03-06-2001	Green et al.	
		US-6,219,243 B1	04-17-2001	Ma et al.	
		US-6,228,452 B1	05-08-2001	Oka et al.	
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FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No. <sup>1</sup>	Foreign Patent Document Country Code <sup>2</sup> - Number <sup>2</sup> - Kind Code <sup>2</sup> (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T*

Examiner Signature	/Tai Nguyen/	Date Considered	09/15/2006
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\*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication.

<sup>1</sup>Applicant's unique citation designation number (optional). <sup>2</sup>See Kinds Codes of USPTO Patent Documents at [www.uspto.gov](http://www.uspto.gov) or MPEP 901.04. <sup>3</sup>Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). <sup>4</sup>For Japanese patent documents, the indication of the year of reign of the Emperor must precede the serial number of the patent document. <sup>5</sup>Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup>Applicant is to place a check mark here if English language Translation is attached.

Based on PTO/SB/08A (08-03) as modified by Blakely, Solokoff, Taylor & Zafman (wr) 08/11/2003.

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Substitute for form 1449A/PTO				<b>Complete if Known</b>	
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>				Application Number	107799,204
				Filing Date	03/11/2004
				First Named Inventor	Joan K. Vrtis
				Art Unit	3729
				Examiner Name	Tai Van Nguyen
Sheet	2	of	3	Attorney Docket Number	42P13111D

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No.†	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T*
TN ↓		BATH, J., Selectron Corp., Lead Free Process Group Update, National Electronics Manufacturing Initiative, Jan. 17, 2001.	
		DEBIASE, JOSEPH D., Organic Solderability Preservatives: Benzotriazoles And Substituted Benzimidazoles, Enthone-OMI Inc., Conference Proceedings; Surface Mount International Conference, September 10, 1996, Abstract page downloaded from Surface Mount Technology Association, SMTA Headquarters - 5200 Willson Road, Suite 215, Edina, Minnesota 55424. 1 page.	
		DEBIASE, JOSEPH D., Organic Solderability Preservatives: Benzotriazoles And Substituted Benzimidazoles, Proceedings Of the SMTA, 1996, Enthone-OMI Inc., New Haven, Connecticut, pages 763-776.	
		HART, K., ET AL., DFE Study Gives Alternative Finishes the Green Light, PC FAB, Oct. 2000.	
		JOHNSON, R.W., ET AL, Thermal Cycle Reliability of Solder Joints to Alternate Plating Finishes, paper from Auburn University, 2000.	
		MORAWSKA, Z, ET AL., Lead-Free Solderability Preservative Coatings for PCBs, Advanced Microelectronics, v. 28, no. 3, May/June 2001.	
TN		PARQUET, D., ET AL., OSP: The High Performance Surface Finish, Electronic Interconnect Conference, 1997.	

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TN		ROMM, D., ET AL., Evaluation of Ni/Pd-Finished ICs with Lead Free Solder Alloys, Texas Instruments Application Report SZZA024, Jan. 2001.	
		SOLBERG, V., Impact of PCB Surface Finish on SMT Assembly Process Yield, Application Note from Tesser Corp.	
		SYED, A., Amkor Technology Corp., Surface Mount Requirements for Advanced Packaging Solutions, 2000.	
		WENGENROTH, KARL, ET AL., OSPS: Addressing Future Surface Finishing Needs, Enthone-OMI, Conference Proceedings, Surface Finishes Forum Conference, May 4, 2000, Abstract page downloaded from Surface Mount Technology Association, SMTA Headquarters - 5200 Willson Road, Suite 215, Edina, Minnesota 55424, 1 page.	
		Double Sided 4Mb SRAM Coupled Cap PBGA Card Assembly Guide, IBM Application Note, Feb. 1998.	
TN		Kester Solder Paste for Surface Mount and General Electronics Assemblies, Online Catalog of Preferred Products, 2001.	

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